Rochester Electronics

Datasheet

Rochester Electronics Manufactured Components

Rochester branded components are manufactured using either die/wafers purchased from the original suppliers or Rochester wafers recreated from the original IP. All recreations are done with the approval of the OCM.

Parts are tested using original factory test programs or Rochester developed test solutions to guarantee product meets or exceed the OCM data sheet.

Quality Overview

- ISO-9001
- AS9120 certification
- Qualified Manufacturers List (QML) MIL-PRF-35835
    - Class Q Military
    - Class V Space Level
- Qualified Suppliers List of Distributors (QSLD)

    - Rochester is a critical supplier to DLA and meets all industry and DLA standards.

Rochester Electronics, LLC is committed to supplying products that satisfy customer expectations for quality and are equal to those originally supplied by industry manufacturers.

The original manufacturer's datasheet accompanying this document reflects the performance and specifications of the Rochester manufactured version of this device. Rochester Electronics guarantees the performance of its semiconductor products to the original OEM specifications. 'Typical' values are for reference purposes only. Certain minimum or maximum ratings may be based on product characterization, design, simulation, or sample testing.

SN74LS165

8-Bit Parallel-to-Serial Shift Register

The SN74LS165 is an 8-bit parallel load or serial-in register with complementary outputs available from the last stage. Parallel inputing occurs asynchronously when the Parallel Load ($\overline{PL}$) input is LOW. With $\overline{PL}$ HIGH, serial shifting occurs on the rising edge of the clock; new data enters via the Serial Data (DS) input. The 2-input OR clock can be used to combine two independent clock sources, or one input can act as an active LOW clock enable.

GUARANTEED OPERATING RANGES

Symbol	Parameter	Min	Typ	Max	Unit
V_{CC}	Supply Voltage	4.75	5.0	5.25	V
T_A	Operating Ambient Temperature Range	0	25	70	°C
I_{OH}	Output Current – High			–0.4	mA
I_{OL}	Output Current – Low			8.0	mA

ON Semiconductor™

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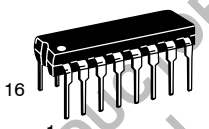
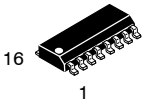
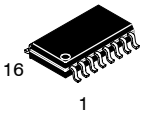
LOW POWER SCHOTTKY



PLASTIC
N SUFFIX
CASE 648



SOIC
D SUFFIX
CASE 751B



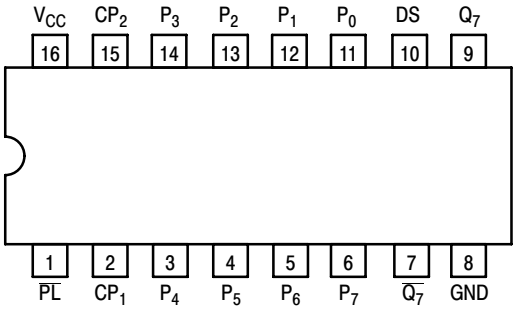
SOEIAJ
M SUFFIX
CASE 966

ORDERING INFORMATION

Device	Package	Shipping
SN74LS165N	16 Pin DIP	2000 Units/Box
SN74LS165D	SOIC–16	38 Units/Rail
SN74LS165DR2	SOIC–16	2500/Tape & Reel
SN74LS165M	SOEIAJ–16	See Note 1
SN74LS165MEL	SOEIAJ–16	See Note 1

1. For ordering information on the EIAJ version of the SOIC package, please contact your local ON Semiconductor representative.

CONNECTION DIAGRAM DIP (TOP VIEW)

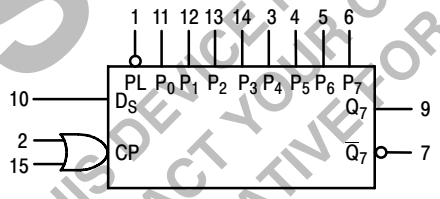


NOTE:
The Flatpak version has the same pinouts (Connection Diagram) as the Dual In-Line Package.

PIN NAMES		LOADING (Note a) HIGH	LOW
CP_1, CP_2	Clock (LOW-to-HIGH Going Edge) Inputs	0.5 U.L.	0.25 U.L.
DS	Serial Data Input	0.5 U.L.	0.25 U.L.
$\overline{PL}$	Asynchronous Parallel Load (Active LOW) Input	1.5 U.L.	0.75 U.L.
P_0 – P_7	Parallel Data Inputs	0.5 U.L.	0.25 U.L.
Q_7	Serial Output from Last State	10 U.L.	5 U.L.
$\overline{Q_7}$	Complementary Output	10 U.L.	5 U.L.

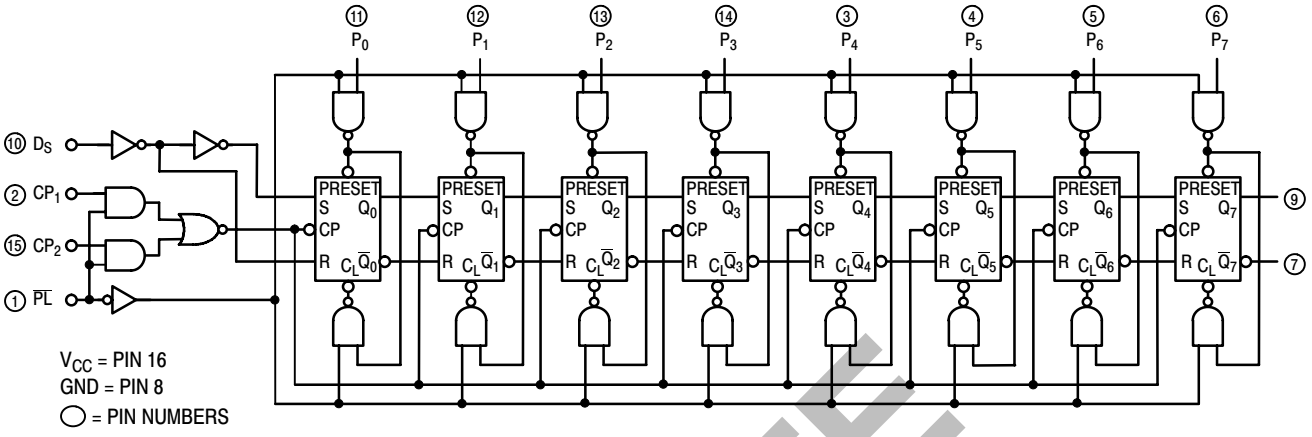
NOTES:
a) 1 TTL Unit Load (U.L.) = 40 μA HIGH/1.6 mA LOW.

LOGIC SYMBOL



V_{CC} = PIN 16
GND = PIN 8

LOGIC DIAGRAM



FUNCTIONAL DESCRIPTION

The SN74LS165 contains eight clocked master/slave RS flip-flops connected as a shift register, with auxiliary gating to provide overriding asynchronous parallel entry. Parallel data enters when the $\overline{PL}$ signal is LOW. The parallel data can change while $\overline{PL}$ is LOW, provided that the recommended setup and hold times are observed.

For clock operation, $\overline{PL}$ must be HIGH. The two clock inputs perform identically; one can be used as a clock inhibit by applying a HIGH signal. To avoid double clocking, however, the inhibit signal should only go HIGH while the clock is HIGH. Otherwise, the rising inhibit signal will cause the same response as a rising clock edge. The flip-flops are edge-triggered for serial operations. The serial input data can change at any time, provided only that the recommended setup and hold times are observed, with respect to the rising edge of the clock.

TRUTH TABLE

$\overline{PL}$	CP		CONTENTS								RESPONSE
	1	2	Q_0	Q_1	Q_2	Q_3	Q_4	Q_5	Q_6	Q_7	
L	X	X	P_0	P_1	P_2	P_3	P_4	P_5	P_6	P_7	Parallel Entry
H	L	↑	D_S	Q_0	Q_1	Q_2	Q_3	Q_4	Q_5	Q_6	Right Shift
H	H	↑	Q_0	Q_1	Q_2	Q_3	Q_4	Q_5	Q_6	Q_7	No Change
H	↑	L	D_S	Q_0	Q_1	Q_2	Q_3	Q_4	Q_5	Q_6	Right Shift
H	↑	H	Q_0	Q_1	Q_2	Q_3	Q_4	Q_5	Q_6	Q_7	No Change

H = HIGH Voltage Level
L = LOW Voltage Level
X = Immaterial

DC CHARACTERISTICS OVER OPERATING TEMPERATURE RANGE (unless otherwise specified)

Symbol	Parameter	Limits			Unit	Test Conditions	
		Min	Typ	Max			
V_{IH}	Input HIGH Voltage	2.0			V	Guaranteed Input HIGH Voltage for All Inputs	
V_{IL}	Input LOW Voltage			0.8	V	Guaranteed Input LOW Voltage for All Inputs	
V_{IK}	Input Clamp Diode Voltage		−0.65	−1.5	V	V_{CC} = MIN, I_{IN} = −18 mA	
V_{OH}	Output HIGH Voltage	2.7	3.5		V	V_{CC} = MIN, I_{OH} = MAX, V_{IN} = V_{IH} or V_{IL} per Truth Table	
V_{OL}	Output LOW Voltage		0.25	0.4	V	I_{OL} = 4.0 mA	V_{CC} = V_{CC} MIN, V_{IN} = V_{IL} or V_{IH} per Truth Table
			0.35	0.5	V	I_{OL} = 8.0 mA	
I_{IH}	Input HIGH Current Other Inputs $\overline{PL}$ Input			 20 60	 μA	V_{CC} = MAX, V_{IN} = 2.7 V	
	Other Inputs $\overline{PL}$ Input			0.1 0.3	mA	V_{CC} = MAX, V_{IN} = 7.0 V	
I_{IL}	Input LOW Current Other Inputs $\overline{PL}$ Input			 −0.4 −1.2	 mA	V_{CC} = MAX, V_{IN} = 0.4 V	
I_{OS}	Short Circuit Current (Note 2)	−20		−100	mA	V_{CC} = MAX	
I_{CC}	Power Supply Current			36	mA	V_{CC} = MAX	

2. Not more than one output should be shorted at a time, nor for more than 1 second.

AC CHARACTERISTICS (T_A = 25°C)

Symbol	Parameter	Limits			Unit	Test Conditions
		Min	Typ	Max		
f_{MAX}	Maximum Input Clock Frequency	25	35		MHz	V_{CC} = 5.0 V C_L = 15 pF
t_{PLH} t_{PHL}	Propagation Delay $\overline{PL}$ to Output		22 22	35 35	ns	
t_{PLH} t_{PHL}	Propagation Delay Clock to Output		27 28	40 40	ns	
t_{PLH} t_{PHL}	Propagation Delay P_7 to Q_7		14 21	25 30	ns	
t_{PLH} t_{PHL}	Propagation Delay P_7 to $\overline{Q}_7$		21 16	30 25	ns	

AC SETUP REQUIREMENTS (T_A = 25°C)

Symbol	Parameter	Limits			Unit	Test Conditions
		Min	Typ	Max		
t_W	CP Clock Pulse Width	25			ns	V_{CC} = 5.0 V
t_W	$\overline{PL}$ Pulse Width	15			ns	
t_s	Parallel Data Setup Time	10			ns	
t_s	Serial Data Setup Time	20			ns	
t_s	CP_1 to CP_2 Setup Time[1]	30			ns	
t_h	Hold Time	0			ns	
t_{rec}	Recovery Time, $\overline{PL}$ to CP	45			ns	

[1] The role of CP_1 and CP_2 in an application may be interchanged.

DEFINITION OF TERMS:

SETUP TIME (t_s) — is defined as the minimum time required for the correct logic level to be present at the logic input prior to the clock transition from LOW-to-HIGH in order to be recognized and transferred to the outputs.

HOLD TIME (t_h) — is defined as the minimum time following the clock transition from LOW-to-HIGH that the logic level must be maintained at the input in order to ensure continued recognition. A negative hold time indicates that the correct logic level may be released prior to the clock transition from LOW-to-HIGH and still be recognized.

RECOVERY TIME (t_{rec}) — is defined as the minimum time required between the end of the $\overline{PL}$ pulse and the clock transition from LOW-to-HIGH in order to recognize and transfer loaded Data to the Q outputs.

AC WAVEFORMS

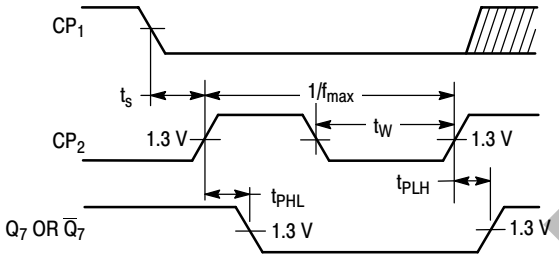


Figure 1.

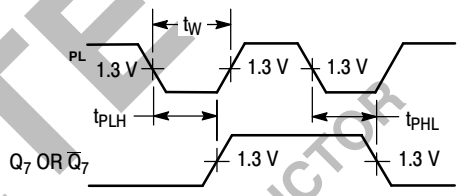


Figure 2.

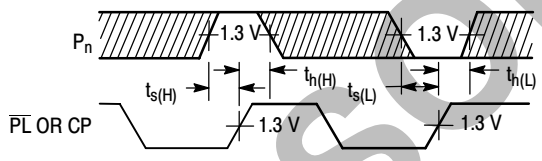


Figure 3.

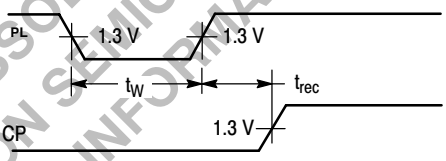
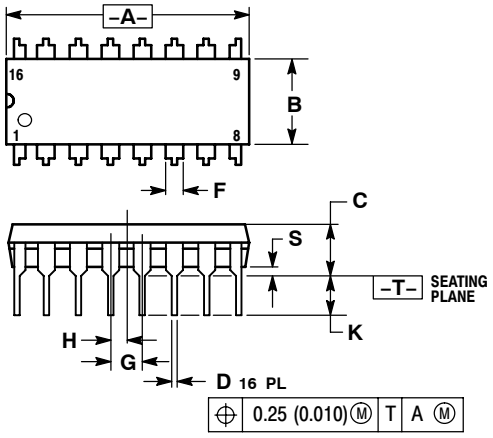


Figure 4.

PACKAGE DIMENSIONS

N SUFFIX
PLASTIC PACKAGE
CASE 648−08
ISSUE R

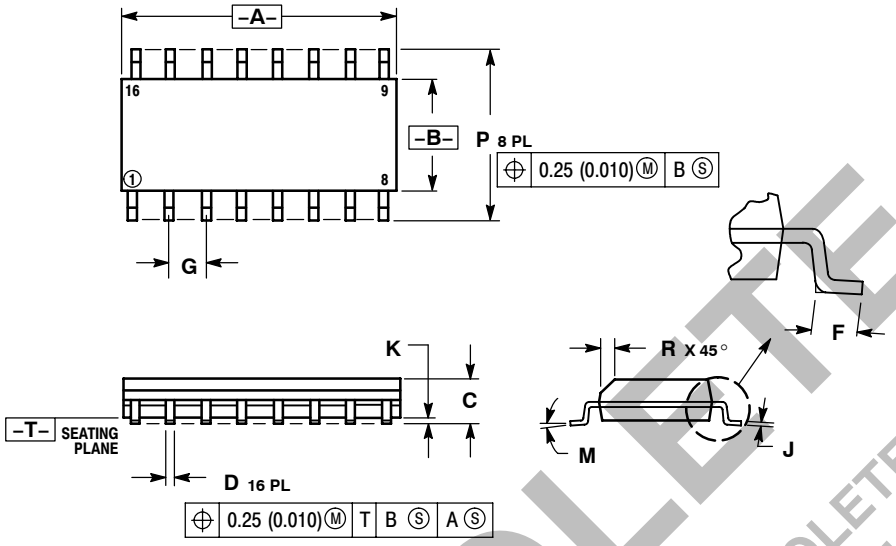


NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
5. ROUNDED CORNERS OPTIONAL.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
A	0.740	0.770	18.80	19.55
B	0.250	0.270	6.35	6.85
C	0.145	0.175	3.69	4.44
D	0.015	0.021	0.39	0.53
F	0.040	0.70	1.02	1.77
G	0.100 BSC		2.54 BSC	
H	0.050 BSC		1.27 BSC	
J	0.008	0.015	0.21	0.38
K	0.110	0.130	2.80	3.30
L	0.295	0.305	7.50	7.74
M	0 °	10 °	0 °	10 °
S	0.020	0.040	0.51	1.01

PACKAGE DIMENSIONS

D SUFFIX
PLASTIC SOIC PACKAGE
CASE 751B–05
ISSUE J

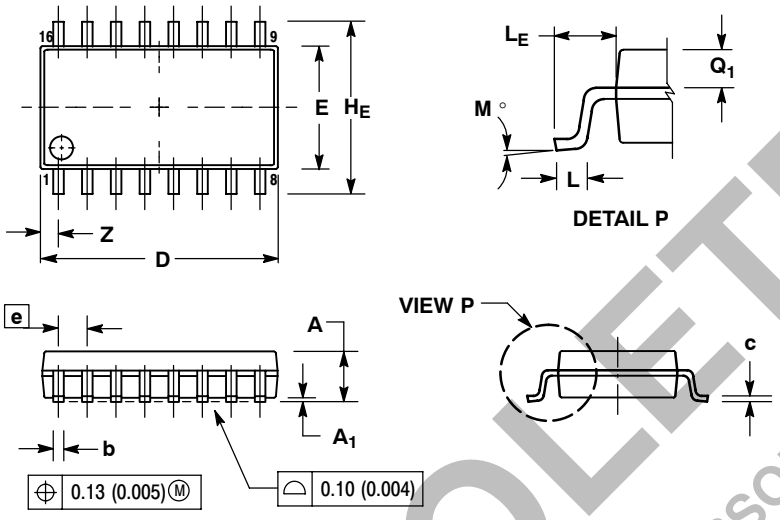


NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
A	9.80	10.00	0.386	0.393
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27 BSC		0.050 BSC	
J	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
M	0°	7°	0°	7°
P	5.80	6.20	0.229	0.244
R	0.25	0.50	0.010	0.019

PACKAGE DIMENSIONS

M SUFFIX
SOEIAJ PACKAGE
CASE 966–01
ISSUE O



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS AND ARE MEASURED AT THE PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
5. THE LEAD WIDTH DIMENSION (b) DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.46 (0.018).

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
A	---	2.05	---	0.081
A_1	0.05	0.20	0.002	0.008
b	0.35	0.50	0.014	0.020
c	0.18	0.27	0.007	0.011
D	9.90	10.50	0.390	0.413
E	5.10	5.45	0.201	0.215
e	1.27 BSC		0.050 BSC	
H_E	7.40	8.20	0.291	0.323
L	0.50	0.85	0.020	0.033
L_E	1.10	1.50	0.043	0.059
M	0 °	10 °	0 °	10 °
Q_1	0.70	0.90	0.028	0.035
Z	---	0.78	---	0.031

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